TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

## **TPCF8102**

# Notebook PC Applications Portable Equipment Applications

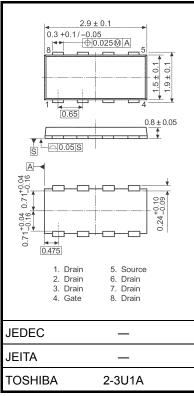
- Low drain-source ON resistance: RDS (ON) = 24 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 14 \text{ S (typ.)}$
- Low leakage current:  $IDSS = -10 \mu A (max) (VDS = -20 V)$
- Enhancement mode:  $V_{th} = -0.5 \text{ to } -1.2 \text{ V}$

 $(V_{DS} = -10 \text{ V}, I_{D} = -200 \text{ }\mu\text{A})$ 

#### **Absolute Maximum Ratings (Ta = 25°C)**

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-20	V	
Drain-gate voltage (R	GS = 20 kΩ)	$V_{DGR}$	-20	V	
Gate-source voltage		V <sub>GSS</sub>	±8	V	
Drain aurrant	DC (Note 1)	ID	-6	Α	
Drain current	Pulsed (Note 1)	I <sub>DP</sub>	-24	A	
Drain power dissipation	on (t = 5 s) (Note 2a)	P <sub>D</sub>	2.5	W	
Drain power dissipation	on (t = 5 s) (Note 2b)	P <sub>D</sub>	0.7	W	
Single pulse avalanch	ne energy (Note 3)	E <sub>AS</sub>	5.9	mJ	
Avalanche current		I <sub>AR</sub>	-3	Α	
Repetitive avalanche	energy (Note 4)	E <sub>AR</sub>	0.25	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	<b>−55~150</b>	°C	

Unit: mm



Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

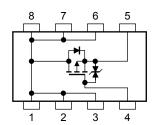
#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R <sub>th (ch-a)</sub>	50.0	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R <sub>th (ch-a)</sub>	178.6	°C/W

Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.

#### **Circuit Configuration**





## **Electrical Characteristics (Ta = 25°C)**

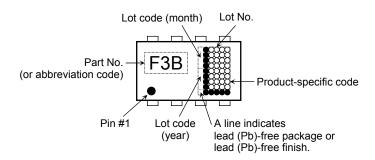
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$	±10		μА		
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			-10	μА	
Drain source breekdown veltere		V <sub>(BR) DSS</sub>	$I_D = -10$ mA, $V_{GS} = 0$ V	-20	_	_	V	
Dialii-source bre	Orain-source breakdown voltage		$I_D = -10$ mA, $V_{GS} = 8$ V	-12	_	_		
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -200 \mu\text{A}$	-0.5	_	-1.2	V	
		R <sub>DS</sub> (ON)	$V_{GS} = -1.8 \text{ V}, I_D = -1.5 \text{ A}$	_	67	90		
Drain-source ON resistance		R <sub>DS</sub> (ON)	$V_{GS} = -2.5 \text{ V}, I_D = -3.0 \text{ A}$	_	36	41	mΩ	
		R <sub>DS</sub> (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -3.0 \text{ A}$	_	24	30		
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -3.0 \text{ A}$	7	14	_	S	
Input capacitance		C <sub>iss</sub>		_	1550	_		
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	215	_	pF	
Output capacitance		Coss		_	265	_		
	Rise time	t <sub>r</sub>	AGS -2 A ID = -3.0 V	_	7	_		
Conitabilita a tima a	Turn-on time	t <sub>on</sub>		_	13	_		
Switching time	Fall time	t <sub>f</sub>	4.7 Ω γ.	_	21	_	ns	
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq -10 \text{ V}$ Duty $\leq$ 1%, $t_W = 10 \mu\text{s}$	_	68	_		
Total gate charge (gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ -16 V, V <sub>GS</sub> = -5 V,		19		_	
Gate-source charge		Q <sub>gs</sub>	$I_D = -6.0 \text{ A}$	_	14		nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	5			

## Source-Drain Ratings and Characteristics (Ta = 25°C)

Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>		_	_	-24	Α
Forward voltage	d voltage (diode) V <sub>DSF</sub> I <sub>D</sub>		$I_{DR} = -6.0 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

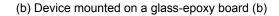
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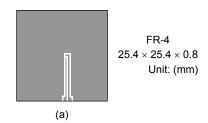
#### Marking (Note 5)

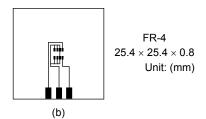


Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)





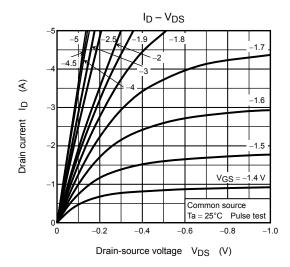


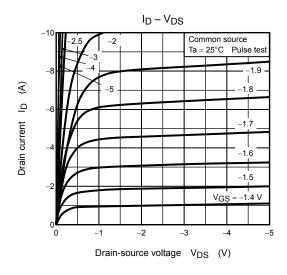
Note 3:  $V_{DD} = -16~V$ ,  $T_{ch} = 25^{\circ}C$  (initial), L = 0.5~mH,  $R_G = 25~\Omega$ ,  $I_{AR} = -3.0~A$ 

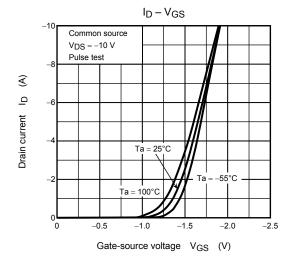
Note 4: Repetitive rating: pulse width limited by maximum channel temperature

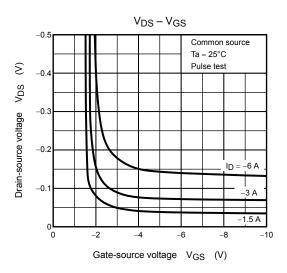
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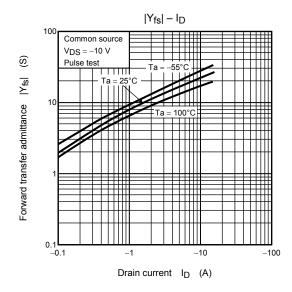
Note 5: A dot on the lower left of the marking indicates Pin 1.

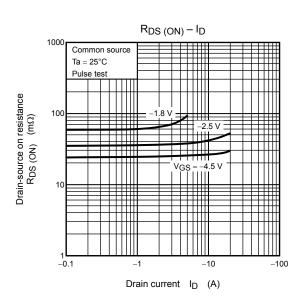


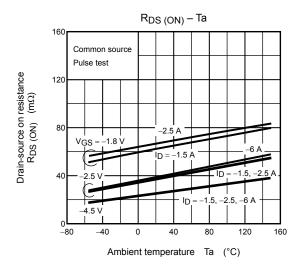


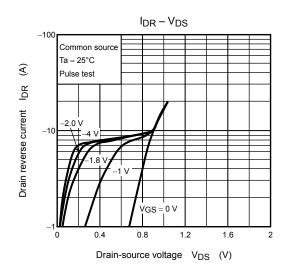


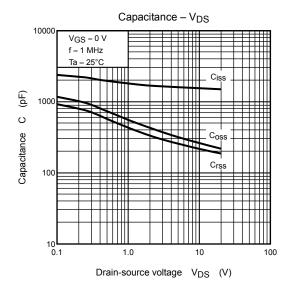


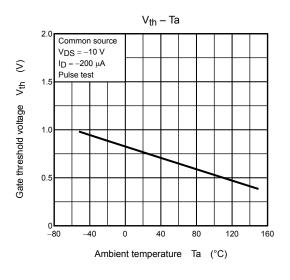


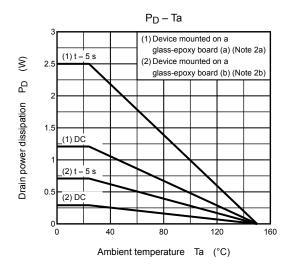


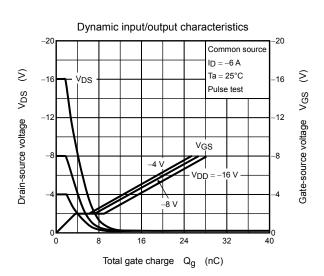




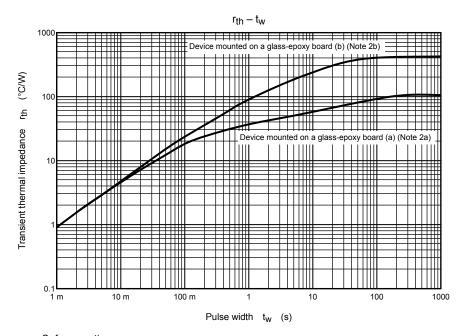


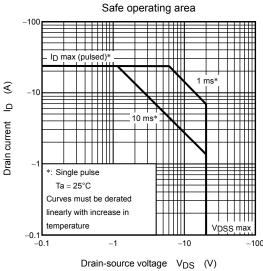






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